Semiconductor Components

Ceramic Packages & Substrates

High-reliability ceramic packages and substrates help to miniaturize components used in smartphones, fiber optics, automotive electronics, headlight LEDs and a wide range of other products. Kyocera utilizes its broad expertise in materials, processing, and design technologies to ensure unparalleled substrate and package performance.

Ceramic Surface-Mount Packages for Electronic Devices

Kyocera's ultra-thin ceramic surface-mount packages for crystal oscillators and other components help to miniaturize smart devices while enhancing their performance.

Optical Components

Kyocera supports today's broadband internet with components such as fiber-optic connectors and laser diode packages that transform signal devices and ensure high data speeds.

Ceramic Packages for Sensors

Ceramic packages for image sensors help create smaller camera modules with higher performance.

LED Lighting for Superiior Color Rendering

LED lighting custom-designed for accurate color rendition is used in galleries and museums, in color inspection, and in horticulture, adding richness to life and communities.

Miniature Crystal Devices

Ultra-small ceramic packages help miniaturize high-functional crystal devices, which are essential in today's electronics. The package shown here protects the crystal with high-speed sealing for high reliability while measuring just 1.2 x 1.1mm.

Organic Packages & Printed Wiring Boards

The rapid advancement of information and communication technologies (ICT) and the expansion of the Internet of Things (IoT) drive the demand for electronic devices with better functionality and performance. Kyocera's organic multilayer packages and printed wiring boards help meet this demand.

Flip-Chip Packages

These flip-chip multilayer packages employ the latest advancements in micro-wiring and low-profile multilayer technology. They support higher functionality and performance in trinaries, routers and mobile communication devices.

Substrates for Wireless Communications

Kyocera's organic substrates are used in telecommunications modules for smartphones and in-board automotive systems, where embedded capacitors and other components are required.

Build-up Wiring Boards

These wiring boards are widely used in PCs, mobile devices, and other products that require high-density surface-mounted boards.

High-Density Multilayer Printed Circuit Boards

These high-performance circuit boards are used in high-end servers and telecommunications systems, where board-level motherboards and backplane boards may require up to 50 layers.

Organic Materials

Our other business domains extend to a wide range of industrial fields, such as digital equipment, automotive manufacturing, energy, and environmental conservation, based on our organic material technology.

Epoxy Encapsulaton Materials for Semiconductors

Kyocera offers new epoxy materials for transfer and compression-molding processes that can create a wide array of lightweight, mass-produced parts.

Die-Attach Pastes

Our full line of die-attach pastes for semiconductors, LEDs and electronic components can meet broad performance requirements, including high thermal conductivity and low curing temperatures.